AMENDMENT TO THE SPECIFICATION

Please change the title of the application to:

FLIP-CHIP PACKAGING METHOD THAT TREATS AN INTERCONNECT SUBSTRATE TO CONTROL STRESS CREATED AT EDGES OF FILL MATERIAL

Please delete the prior abstract and add the following new abstract.

A flip-chip packaging method for a semiconductor device treats a portion of an interconnect substrate so that a fill material when liquid beads on the treated portion of the interconnect substrate. When the fill material is dispensed on the interconnect substrate to fill a gap under the semiconductor device, the beading of the fill material prevents formation of fillets that might otherwise create a variation in the thermal coefficient of expansion of fill material and/or warp the interconnect substrate. The treated portion of the interconnect substrate can be roughened or coated with a material that differs from other portions of the interconnect substrate and thereby causes beading.

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